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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	4KB (2K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2220t-i-so

TABLE 2-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal	• •	apacitor Values ested:	
	Freq	C1	C2	
LP	32 kHz	33 pF	33 pF	
	200 kHz	15 pF	15 pF	
XT	1 MHz	33 pF	33 pF	
	4 MHz	27 pF	27 pF	
HS	4 MHz	27 pF	27 pF	
	8 MHz	22 pF	22 pF	
	20 MHz	15 pF	15 pF	

Capacitor values are for design guidance only.

These capacitors were tested with the crystals listed below for basic start-up and operation. **These values are not optimized.**

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

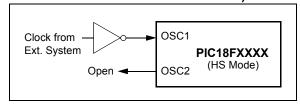
See the notes following this table for additional information.

Crystals Used:				
32 kHz	4 MHz			
200 kHz	8 MHz			
1 MHz	20 MHz			

- **Note 1:** Higher capacitance increases the stability of the oscillator, but also increases the start-up time.
 - 2: When operating below 3V VDD, or when using certain ceramic resonators at any voltage, it may be necessary to use the HS mode or switch to a crystal oscillator.
 - 3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
 - **4:** Rs may be required to avoid overdriving crystals with low drive level specification.
 - **5:** Always verify oscillator performance over the VDD and temperature range that is expected for the application.

An external clock source may also be connected to the OSC1 pin in the HS mode, as shown in Figure 2-2.

FIGURE 2-2: EXTERNAL CLOCK INPUT OPERATION (HS OSC CONFIGURATION)



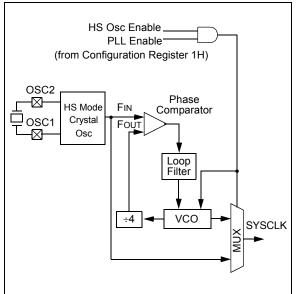
2.3 HSPLL

A Phase Locked Loop (PLL) circuit is provided as an option for users who wish to use a lower frequency crystal oscillator circuit, or to clock the device up to its highest rated frequency from a crystal oscillator. This may be useful for customers who are concerned with EMI due to high-frequency crystals.

The HSPLL mode makes use of the HS mode oscillator for frequencies up to 10 MHz. A PLL then multiplies the oscillator output frequency by 4 to produce an internal clock frequency up to 40 MHz.

The PLL is enabled only when the oscillator Configuration bits are programmed for HSPLL mode. If programmed for any other mode, the PLL is not enabled.

FIGURE 2-3: PLL BLOCK DIAGRAM



3.3.3 RC IDLE MODE

In RC_IDLE mode, the CPU is disabled but the peripherals continue to be clocked from the internal oscillator block using the INTOSC multiplexer. This mode allows for controllable power conservation during Idle periods.

This mode is entered by setting the IDLEN bit, setting SCS1 (SCS0 is ignored) and executing a SLEEP instruction. The INTOSC multiplexer may be used to select a higher clock frequency by modifying the IRCF bits before executing the SLEEP instruction. When the clock source is switched to the INTOSC multiplexer (see Figure 3-7), the primary oscillator is shut down and the OSTS bit is cleared.

If the IRCF bits are set to a non-zero value (thus enabling the INTOSC output), the IOFS bit becomes set after the INTOSC output becomes stable, in about 1 ms. Clocks to the peripherals continue while the INTOSC source stabilizes. If the IRCF bits were previously at a non-zero value before the SLEEP instruction

was executed and the INTOSC source was already stable, the IOFS bit will remain set. If the IRCF bits are all clear, the INTOSC output is not enabled and the IOFS bit will remain clear; there will be no indication of the current clock source.

When a wake-up event occurs, the peripherals continue to be clocked from the INTOSC multiplexer. After a 10 μs delay following the wake-up event, the CPU begins executing code, being clocked by the INTOSC multiplexer. The microcontroller operates in RC_RUN mode until the primary clock becomes ready. When the primary clock becomes ready, a clock switch back to the primary clock occurs (see Figure 3-8). When the clock switch is complete, the IOFS bit is cleared, the OSTS bit is set and the primary clock is providing the system clock. The IDLEN and SCS bits are not affected by the wake-up. The INTRC source will continue to run if either the WDT or the Fail-Safe Clock Monitor is enabled.



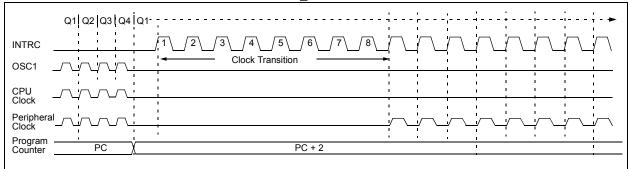
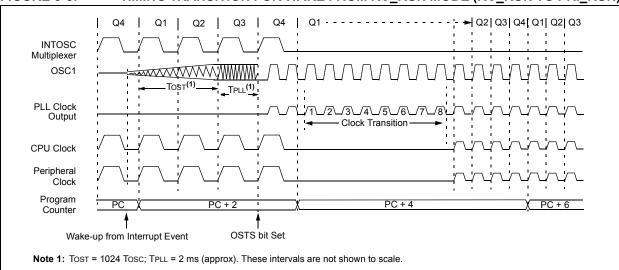


FIGURE 3-8: TIMING TRANSITION FOR WAKE FROM RC_RUN MODE (RC_RUN TO PRI_RUN)



3.6.1 EXAMPLE – USART

An adjustment may be indicated when the USART begins to generate framing errors or receives data with errors while in Asynchronous mode. Framing errors indicate that the system clock frequency is too high – try decrementing the value in the OSCTUNE register to reduce the system clock frequency. Errors in data may suggest that the system clock speed is too low – increment OSCTUNE.

3.6.2 EXAMPLE - TIMERS

This technique compares system clock speed to some reference clock. Two timers may be used; one timer is clocked by the peripheral clock, while the other is clocked by a fixed reference source, such as the Timer1 oscillator.

Both timers are cleared but the timer clocked by the reference generates interrupts. When an interrupt occurs, the internally clocked timer is read and both timers are cleared. If the internally clocked timer value is greater than expected, then the internal oscillator block is running too fast – decrement OSCTUNE.

3.6.3 EXAMPLE – CCP IN CAPTURE MODE

A CCP module can use free-running Timer1 (or Timer3), clocked by the internal oscillator block and an external event with a known period (i.e., AC power frequency). The time of the first event is captured in the CCPRxH:CCPRxL registers and is recorded for use later. When the second event causes a capture, the time of the first event is subtracted from the time of the second event. Since the period of the external event is known, the time difference between events can be calculated.

If the measured time is much greater than the calculated time, the internal oscillator block is running too fast – decrement OSCTUNE. If the measured time is much less than the calculated time, the internal oscillator block is running too slow – increment OSCTUNE.

5.0 MEMORY ORGANIZATION

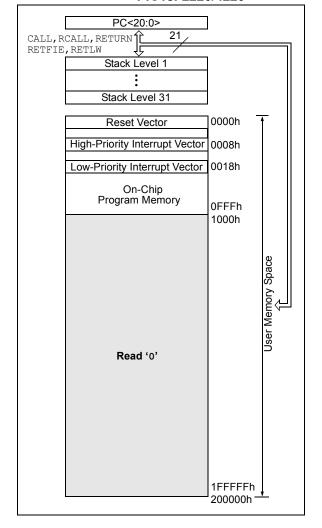
There are three memory types in enhanced MCU devices. These memory types are:

- Program Memory
- · Data RAM
- Data EEPROM

Data and program memory use separate busses which allow for concurrent access of these types.

Additional detailed information for Flash program memory and data EEPROM is provided in Section 6.0 "Flash Program Memory" and Section 7.0 "Data EEPROM Memory", respectively.

FIGURE 5-1: PROGRAM MEMORY MAP
AND STACK FOR
PIC18F2220/4220



5.1 Program Memory Organization

A 21-bit program counter is capable of addressing the 2-Mbyte program memory space. Accessing a location between the physically implemented memory and the 2-Mbyte address will cause a read of all '0's (a NOP instruction).

The PIC18F2220 and PIC18F4220 each have 4 Kbytes of Flash memory and can store up to 2,048 single-word instructions.

The PIC18F2320 and PIC18F4320 each have 8 Kbytes of Flash memory and can store up to 4,096 single-word instructions.

The Reset vector address is at 0000h and the interrupt vector addresses are at 0008h and 0018h.

The Program Memory Maps for PIC18F2220/4220 and PIC18F2320/4320 devices are shown in Figure 5-1 and Figure 5-2, respectively.

FIGURE 5-2: PROGRAM MEMORY MAP
AND STACK FOR
PIC18F2320/4320

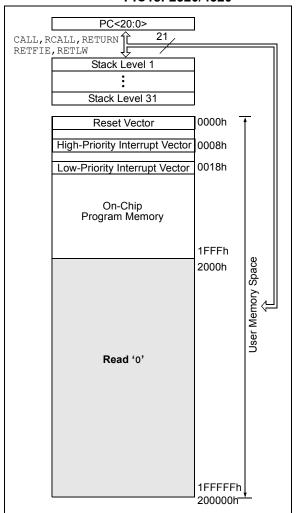


TABLE 10-1: PORTA FUNCTIONS

Name	Bit#	Buffer	Function
RA0/AN0	bit 0	TTL	Input/output or analog input.
RA1/AN1	bit 1	TTL	Input/output or analog input.
RA2/AN2/VREF-/CVREF	bit 2	TTL	Input/output, analog input, VREF- or comparator VREF output.
RA3/AN3/VREF+	bit 3	TTL	Input/output, analog input or VREF+.
RA4/T0CKI/C1OUT	bit 4	ST	Input/output, external clock input for Timer0 or Comparator 1 output. Output is open-drain type.
RA5/AN4/SS/LVDIN/C2OUT	bit 5	TTL	Input/output, analog input, slave select input for Master Synchronous Serial Port, Low-Voltage Detect input or Comparator 2 output.
OSC2/CLKO/RA6	bit 6	TTL	OSC2, clock output or I/O pin.
OSC1/CLKI/RA7	bit 7	TTL	OSC1, clock input or I/O pin.

Legend: TTL = TTL input, ST = Schmitt Trigger input

TABLE 10-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
PORTA	RA7 ⁽¹⁾	RA6 ⁽¹⁾	RA5	RA4	RA3	RA2	RA1	RA0	xx0x 0000	uu0u 0000
LATA	LATA7 ⁽¹⁾	LATA6 ⁽¹⁾	LATA Data	Latch Reg	gister				xxxx xxxx	uuuu uuuu
TRISA	TRISA7 ⁽¹⁾	TRISA6 ⁽¹⁾	PORTA D	ata Directio	n Register				1111 1111	1111 1111
ADCON1	_	_	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	00 0000	00 0000
CMCON	C2OUT	C10UT	C2INV	C1INV	CIS	CM2	CM1	CM0	0000 0111	0000 0111
CVRCON	CVREN	CVROE	CVRR	_	CVR3	CVR2	CVR1	CVR0	000- 0000	000- 0000

Legend: x = unknown, u = unchanged, x = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

Note 1: RA7:RA6 and their associated latch and data direction bits are enabled as I/O pins based on oscillator configuration; otherwise, they are read as '0'.

TABLE 15-3: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, TIMER1 AND TIMER3

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000	0000 000u
PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 000	0000 0000
PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 000	0000 0000
IPR1	PSPIP ⁽¹⁾	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	1111 111	1111 1111
TRISC	PORTC D	ata Direction	Register						1111 111	1111 1111
TMR1L	Holding Re	egister for th	e Least Sigr	nificant Byte	of the 16-bit	TMR1 Reg	gister		xxxx xxxx	uuuu uuuu
TMR1H	Holding Re	egister for th	e Most Sign	ificant Byte	of the 16-bit	TMR1 Reg	ister		xxxx xxxx	uuuu uuuu
T1CON	RD16	T1RUN	T1CKPS1	T1CKPS0	T10SCEN	T1SYNC	TMR1CS	TMR10N	0000 000	uuuu uuuu
CCPR1L	Capture/C	ompare/PW	M Register	I (LSB)					xxxx xxx	uuuu uuuu
CCPR1H	Capture/C	ompare/PWI	M Register	I (MSB)					xxxx xxx	uuuu uuuu
CCP1CON	_	_	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 000	00 0000
CCPR2L	Capture/C	ompare/PW	M Register 2	2 (LSB)					xxxx xxx	uuuu uuuu
CCPR2H	Capture/C	ompare/PWI	M Register 2	2 (MSB)					xxxx xxx	uuuu uuuu
CCP2CON	_	_	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	00 000	00 0000
PIR2	OSCFIF	CMIF	_	EEIF	BCLIF	LVDIF	TMR3IF	CCP2IF	00-0 000	00-0 0000
PIE2	OSCFIE	CMIE	_	EEIE	BCLIE	LVDIE	TMR3IE	CCP2IE	00-0 000	00-0 0000
IPR2	OSCFIP	CMIP	_	EEIP	BCLIP	LVDIP	TMR3IP	CCP2IP	11-1 111	11-1 1111
TMR3L	Holding Register for the Least Significant Byte of the 16-bit TMR3 Register								xxxx xxx	uuuu uuuu
TMR3H	Holding Re	egister for th	e Most Sign	ificant Byte	of the 16-bit	TMR3 Reg	ister		xxxx xxx	uuuu uuuu
T3CON	RD16	T3CCP2	T3CKPS1	T3CKPS0	T3CCP1	T3SYNC	TMR3CS	TMR3ON	0000 000	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by Capture and Timer1.

Note 1: These bits are reserved on the PIC18F2X20 devices; always maintain these bits clear.

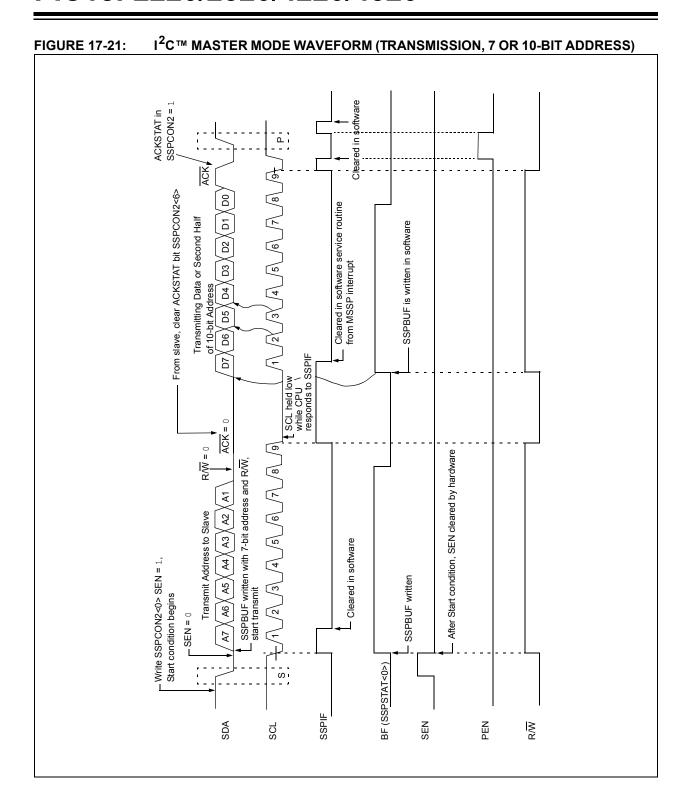


FIGURE 18-2: ASYNCHRONOUS TRANSMISSION

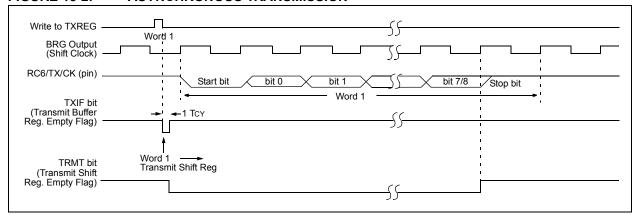


FIGURE 18-3: ASYNCHRONOUS TRANSMISSION (BACK TO BACK)

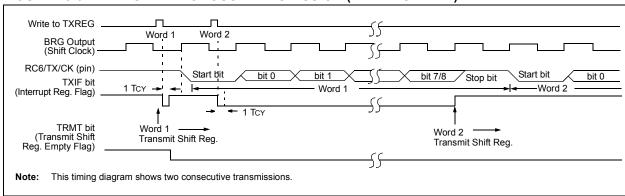


TABLE 18-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP ⁽¹⁾	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	1111 1111	1111 1111
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
TXREG	USART Transmit Register							0000 0000	0000 0000	
TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
SPBRG	Baud Rate Generator Register							0000 0000	0000 0000	

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for asynchronous transmission.

Note 1: The PSPIF, PSPIE and PSPIP bits are reserved on the PIC18F2X20 devices; always maintain these bits clear.

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (AVDD and AVSS), or the voltage level on the RA3/AN3/ VREF+ and RA2/AN2/VREF-/CVREF pins.

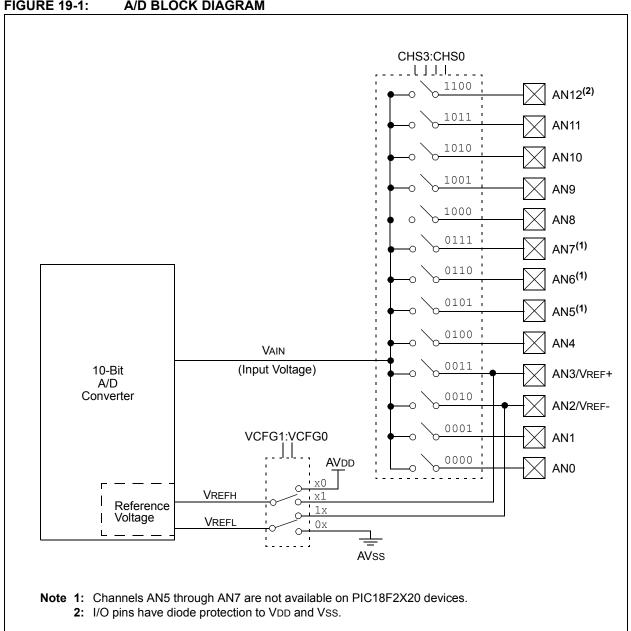
The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in SLEEP, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the converter which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D converter can be configured as an analog input or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH/ADRESL registers, the GO/DONE bit (ADCON0 register) is cleared and A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 19-1.

FIGURE 19-1: A/D BLOCK DIAGRAM



19.5 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the ACQT2:ACQT0 and ADCS2:ADCS0 bits in ADCON2 should be updated in accordance with the power-managed mode clock that will be used. After the power-managed mode is entered (either of the power-managed Run modes), an A/D acquisition or conversion may be started. Once an acquisition or conversion is started, the device should continue to be clocked by the same power-managed mode clock source until the conversion has been completed. If desired, the device may be placed into the corresponding power-managed Idle mode during the conversion.

If the power-managed mode clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D RC clock to be selected. If bits ACQT2:ACQT0 are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction and entry to Sleep mode. The IDLEN and SCS bits in the OSCCON register must have already been cleared prior to starting the conversion.

19.6 Configuring Analog Port Pins

The ADCON1, TRISA, TRISB and TRISE registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS3:CHS0 bits and the TRIS bits.

- Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs will convert an analog input. Analog levels on a digitally configured input will be accurately converted.
 - 2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.
 - 3: The PBADEN bit in the Configuration register configures PORTB pins to reset as analog or digital pins by controlling how the PCFG0 bits in ADCON1 are reset.

NOTES:

TABLE 24-2: PIC18FXXX INSTRUCTION SET

Mnemo	onic,	Description	Cycles	16-E	Bit Instr	uction V	Vord	Status	Notes
Opera	nds	Description	Cycles	MSb			LSb	Affected	Notes
BYTE-ORI	ENTED	FILE REGISTER OPERATIONS							
ADDWF	f, d, a	Add WREG and f	1	0010	01da	ffff	ffff	C, DC, Z, OV, N	1, 2
ADDWFC	f, d, a	Add WREG and Carry bit to f	1	0010	00da	ffff	ffff	C, DC, Z, OV, N	1, 2
ANDWF	f, d, a	AND WREG with f	1	0001	01da	ffff	ffff	Z, N	1,2
CLRF	f, a	Clear f	1	0110	101a	ffff	ffff	Z	2
COMF	f, d, a	Complement f	1	0001	11da	ffff	ffff	Z, N	1, 2
CPFSEQ	f, a	Compare f with WREG, Skip =	1 (2 or 3)	0110	001a	ffff	ffff	None	4
CPFSGT	f, a	Compare f with WREG, Skip >	1 (2 or 3)	0110	010a	ffff	ffff	None	4
CPFSLT	f, a	Compare f with WREG, Skip <	1 (2 or 3)	0110	000a	ffff	ffff	None	1, 2
DECF	f, d, a	Decrement f	1	0000	01da	ffff	ffff	C, DC, Z, OV, N	1, 2, 3, 4
DECFSZ	f, d, a	Decrement f, Skip if 0	1 (2 or 3)	0010	11da	ffff	ffff	None	1, 2, 3, 4
DCFSNZ	f, d, a	Decrement f, Skip if Not 0	1 (2 or 3)	0100	11da	ffff	ffff	None	1, 2
INCF	f, d, a	Increment f	1 ` ′	0010	10da	ffff	ffff	C, DC, Z, OV, N	1, 2, 3, 4
INCFSZ	f, d, a	Increment f, Skip if 0	1 (2 or 3)	0011	11da	ffff	ffff	None	4
INFSNZ	f, d, a	Increment f, Skip if Not 0	1 (2 or 3)	0100	10da	ffff	ffff	None	1, 2
IORWF	f, d, a	Inclusive OR WREG with f	1 ` ′	0001	00da	ffff	ffff	Z, N	1, 2
MOVF	f, d, a	Move f	1	0101	00da	ffff		Z, N	1
MOVFF	f_s, f_d	Move f _s (source) to 1st word	2	1100	ffff	ffff	ffff	None	
	3, a	f _d (destination) 2nd word		1111	ffff	ffff	ffff		
MOVWF	f, a	Move WREG to f	1	0110	111a	ffff	ffff	None	
MULWF	f, a	Multiply WREG with f	1	0000	001a	ffff	ffff	None	
NEGF	f, a	Negate f	1	0110	110a	ffff	ffff	C, DC, Z, OV, N	1, 2
RLCF	f, d, a	Rotate Left f through Carry	1	0011	01da	ffff	ffff	C, Z, N	·
RLNCF	f, d, a	Rotate Left f (No Carry)	1	0100	01da	ffff	ffff	Z, N	1, 2
RRCF	f, d, a	Rotate Right f through Carry	1	0011	00da	ffff	ffff	C, Z, N	·
RRNCF	f, d, a	Rotate Right f (No Carry)	1	0100	00da	ffff	ffff	Z, N	
SETF	f, a	Set f	1	0110	100a	ffff	ffff	None	
SUBFWB	f, d, a	Subtract f from WREG with	1	0101	01da	ffff	ffff	C, DC, Z, OV, N	1. 2
	, ,	Borrow							,
SUBWF	f, d, a	Subtract WREG from f	1	0101	11da	ffff	ffff	C, DC, Z, OV, N	
SUBWFB	f, d, a	Subtract WREG from f with	1	0101	10da	ffff	ffff		1, 2
	, - , -	Borrow							,
SWAPF	f, d, a	Swap Nibbles in f	1	0011	10da	ffff	ffff	None	4
TSTFSZ	f, a	Test f, Skip if 0	1 (2 or 3)	0110	011a	ffff	ffff	None	1, 2
XORWF	f, d, a	Exclusive OR WREG with f	1	0001	10da	ffff	ffff	Z, N	,
		E REGISTER OPERATIONS	-	0001	1000				
BCF	f, b, a	Bit Clear f	1	1001	bbba	ffff	ffff	None	1, 2
BSF	f, b, a	Bit Set f	1		bbba	ffff	ffff	None	1, 2
BTFSC		Bit Test f, Skip if Clear	1 (2 or 3)	1011	bbba	ffff	ffff	None	3, 4
BTFSS		Bit Test f, Skip if Set	1 (2 or 3)	1011	bbba	ffff	ffff	None	3, 4
BTG	f, d, a	Bit Toggle f	1 (2 01 3)						3, 4 1, 2
ыс	ı, u, a	Dit roggie i	ı	OTTI	bbba	ffff	ffff	None	1,∠

Note 1: When a PORT register is modified as a function of itself (e.g., MOVF PORTB, 1, 0), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

- **4:** Some instructions are 2-word instructions. The second word of these instructions will be executed as a NOP unless the first word of the instruction retrieves the information embedded in these 16 bits. This ensures that all program memory locations have a valid instruction.
- 5: If the table write starts the write cycle to internal memory, the write will continue until terminated.

^{2:} If this instruction is executed on the TMR0 register (and where applicable, d = 1), the prescaler will be cleared if assigned.

^{3:} If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

BNC Branch if Not Carry

Syntax: [label] BNC n Operands: $-128 \le n \le 127$ Operation: if Carry bit is '0',

 $(PC) + 2 + 2n \rightarrow PC$

Status Affected: None

Encoding: 1110 0011 nnnn nnnn

Description: If the Carry bit is '0', then the

program will branch.

The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a two-cycle instruction.

Words: 1 Cycles: 1(2)

Q Cycle Activity:

If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal	Process	Write to PC
	ʻn'	Data	
No	No	No	No
operation	operation	operation	operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal	Process	No
	'n'	Data	operation

Example: HERE BNC Jump

Before Instruction

PC = address (HERE)

After Instruction

If Carry = 0;

PC = address (Jump)

If Carry = 1; PC = address (HERE + 2) BNN Branch if Not Negative

Syntax: [label] BNN n Operands: $-128 \le n \le 127$ Operation: if Negative bit is '0',

Status Affected: None

Encoding: 1110 0111 nnnn nnnn

 $(PC) + 2 + 2n \rightarrow PC$

Description: If the Negative bit is '0', then the

program will branch.

The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal	Process	Write to PC
	ʻn'	Data	
No	No	No	No
operation	operation	operation	operation

If No Jump:

	Q1	Q2	Q3	Q4
I	Decode	Read literal	Process	No
		ʻn'	Data	operation

Example: HERE BNN Jump

Before Instruction

PC = address (HERE)

After Instruction

If Negative = 0;

PC = address (Jump)

If Negative = 1; PC = address (HERE + 2)

MOVFF Move f to f

Syntax: [label] MOVFF f_s,f_d

Operands: $0 \le f_s \le 4095$

 $0 \leq f_d \leq 4095$

Operation: $(f_s) \rightarrow f_d$ Status Affected: None

Encoding: 1st word (source) 2nd word (destin.)

	1100	ffff	ffff	ffffs
1	1111	ffff	ffff	ffffd

Description:

The contents of source register ' f_s ' are moved to destination register ' f_d '. Location of source ' f_s ' can be anywhere in the 4096-byte data space (000h to FFFh) and location of destination ' f_d ' can also be anywhere from 000h to FFFh. Either source or destination can be W (a useful special situation). MOVFF is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port).

The MOVFF instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register.

The MOVFF instruction should not be used to modify interrupt settings while any interrupt is enabled (see Page 87).

Words: 2 Cycles: 2 (3)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f' (src)	Process Data	No operation
Decode	No operation No dummy read	No operation	Write register 'f' (dest)

Example: MOVFF REG1, REG2

Before Instruction

REG1 = 0x33
 REG2 = 0x11

After Instruction

REG1 = 0x33, REG2 = 0x33

MOVLB Move Literal to Low Nibble in BS	MOVLB	Move Literal to Low Nibble in BS
--	-------	----------------------------------

Syntax: [label] MOVLB k

Status Affected: None

Encoding: 0000 0001 kkkk kkkk

Description: The 8-bit literal 'k' is loaded into the Bank Select Register (BSR).

Words: 1
Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal	Process	Write
	'k'	Data	literal 'k' to
			BSR

Example: MOVLB 5

Before Instruction

BSR register = 0x02

After Instruction

BSR register = 0x05

NEGF	Negate f				
Syntax:	[label] NEGF f[,a]				
Operands:	$0 \le f \le 255$ $a \in [0,1]$				
Operation:	$(\overline{f}) + 1 \rightarrow f$				
Status Affected:	N, OV, C, DC, Z				
Encoding:	0110 110a ffff ffff				
Description:	Location 'f' is negated using two's complement. The result is placed in the data memory location 'f'. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value.				

Words: 1 Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read	Process	Write
	register 'f'	Data	register 'f'

Example: NEGF REG, 1

Before Instruction

REG = $0011 \ 1010 \ [0x3A]$

After Instruction

REG = $1100 \ 0110 \ [0xC6]$

NOP	No Operation				
Syntax:	[label]	NOP			
Operands:	None				
Operation:	No opera	ition			
Status Affected:	None				
Encoding:	0000	0000	0000	0000	
	1111	XXXX	XXXX	XXXX	
Description:	No opera	ition.			
Words:	1				
Cycles:	1				
Q Cycle Activity:					
Q1	Q2	Q3	3	Q4	

No

operation

No

operation

No

operation

Example:

Decode

None.

26.2 DC Characteristics: Power-Down and Supply Current PIC18F2220/2320/4220/4320 (Industrial) PIC18LF2220/2320/4220/4320 (Industrial) (Continued)

PIC18LF2220/2320/4220/4320 (Industrial) PIC18F2220/2320/4220/4320 (Industrial, Extended)		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{Ta} \le +85^{\circ}\text{C}$ for industrial					
		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$ for extended					
Param No.	Device	Тур	Max	Units		Conditio	ns
	Supply Current (IDD) ^(2,3)						
	PIC18LF2X20/4X20	440	600	μА	-40°C		
		450	600	μА	+25°C	VDD = 2.0V	
		460	600	μА	+85°C		
	PIC18LF2X20/4X20	0.80	1.0	mA	-40°C		
		0.78	1.0	mA	+25°C	VDD = 3.0V	Fosc = 4 MHz (PRI RUN ,
		0.77	1.0	mA	+85°C		EC oscillator)
	All devices	1.6	2.0	mA	-40°C		,
		1.5	2.0	mA	+25°C	VDD = 5.0V	
		1.5	2.0	mA	+85°C	VDD = 3.0V	
	Extended devices	1.5	2.0	mA	+125°C		
	Extended devices	6.3	9.0	mA	+125°C	V _{DD} = 4.2V	Fosc = 25 MHz (PRI RUN ,
		7.9	10.0	mA	+125°C	VDD = 5.0V	EC oscillator)
	All devices	9.5	12	mA	-40°C		
		9.7	12	mA	+25°C	VDD = 4.2V	
		9.9	12	mA	+85°C		Fosc = 40 MHz
	All devices	11.9	15	mA	-40°C		(PRI_RUN , EC oscillator)
		12.1	15	mA	+25°C	VDD = 5.0V	,
		12.3	15	mA	+85°C		

Legend: Shading of rows is to assist in readability of the table.

- Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or Vss and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).
 - 2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;

MCLR = VDD; WDT enabled/disabled as specified.

- 3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.
- 4: Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

APPENDIX B: DEVICE

DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Features	PIC18F2220	PIC18F2320	PIC18F4220	PIC18F4320
Program Memory (Bytes)	4096	8192	4096	8192
Program Memory (Instructions)	2048	4096	2048	4096
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/Compare/ PWM Modules	0	0	1	1
Parallel Communications (PSP)	No	No	Yes	Yes
10-bit Analog-to-Digital Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Packages	28-Pin SPDIP 28-Pin SOIC	28-Pin SPDIP 28-Pin SOIC	40-Pin PDIP 44-Pin TQFP 44-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN

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